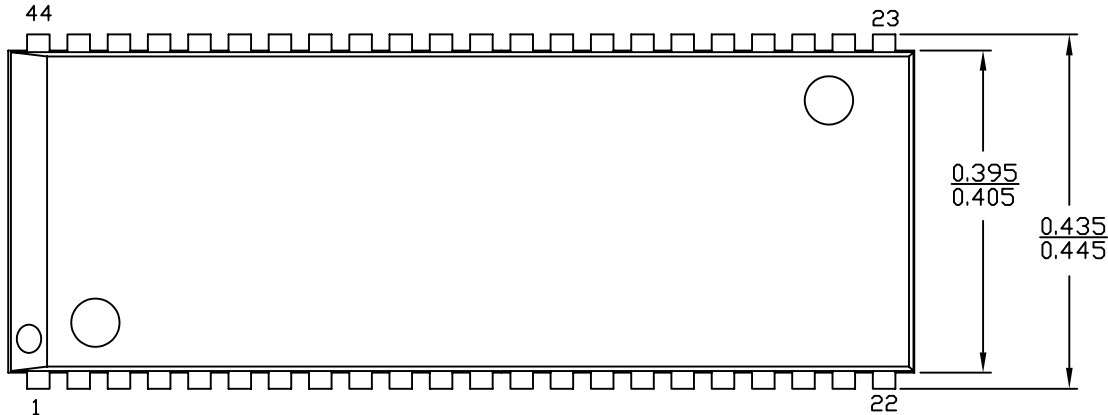


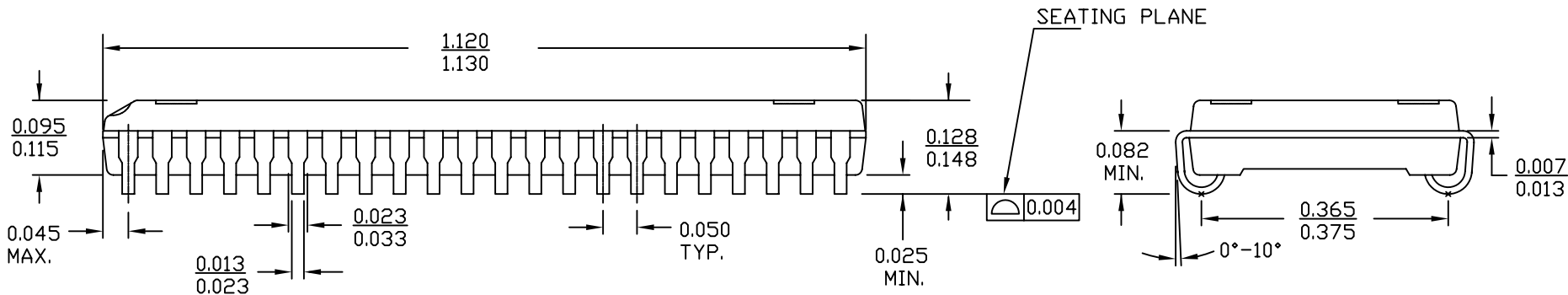
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	43728	NEW RELEASE	07/17/96	N/A
1	-	*A	49485	CHG. TITLE	05/29/97	N/A
1	-	*B	54476	CHG. PKG HEIGH & LEAD WIDTH	02/09/98	N/A
1	-	*C	2833453	Changed template, & title from 44LD (400 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 44LD SOJ 400 MILS V44.4.	12/28/09	QAD
1	-	*D	3352935	Update spec for sunset review, no changed	08/24/11	QAD
1	-	*E	3726137	Sunset Review, Added Package Weight – Refer to PMDD spec.	08/28/12	QAD


44 Lead (400 MIL) MOLDED SOJ



DIMENSIONS IN INCHES MIN.  
MAX.

Package Weight - Refer to PMDD spec.



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON:  DECIMALS .XX ± 0.05 .XXX ± .XXXX +  ANGLES ± 1°		DESIGNED BY	MTN	DATE	02/09/98
		DRAWN BY	ROWI	DATE	08/28/12
		CHECKED BY	QAD	DATE	08/28/12
		APPROVED BY	EDCA	DATE	08/28/12
MATERIAL	N/A	APPROVED BY	QAD	DATE	08/28/12
FINISH	N/A	APPROVED BY	NA	DATE	NA
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				PACKAGE OUTLINE, 44LD SOJ 400 MILS V44.4	
SIZE	A	PART NO.	V44.4	DWG NO	51-85082
SCALED TO FIT				REV	*E
				SHEET 1 OF 1	